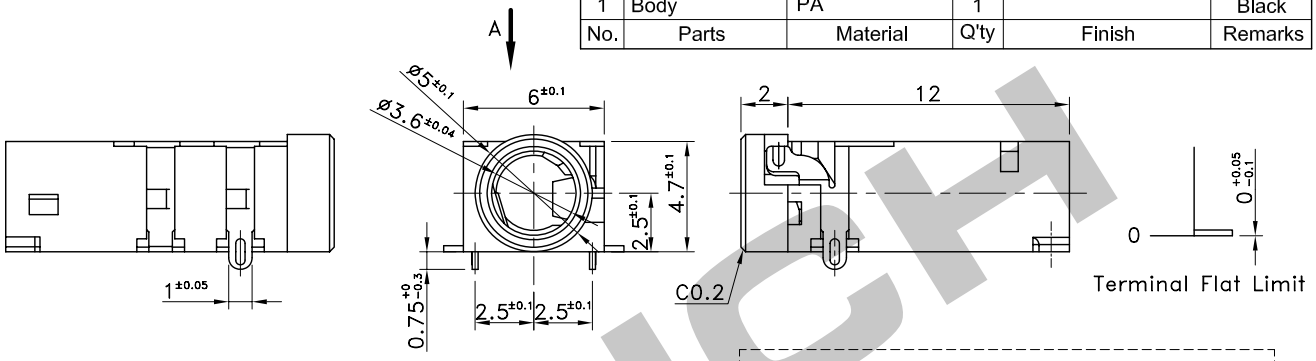
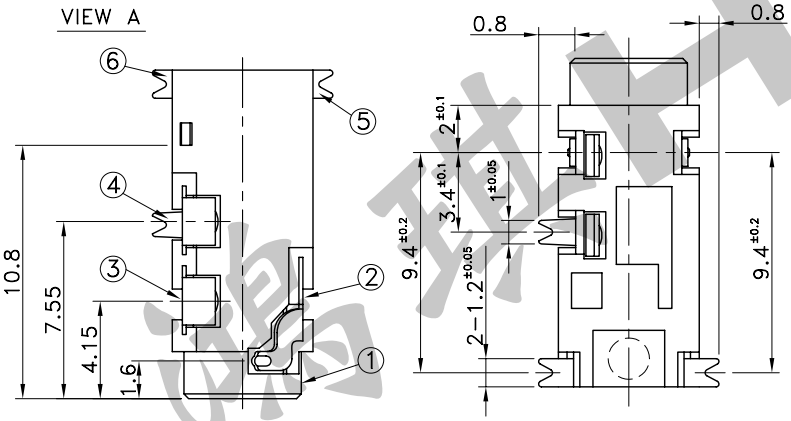
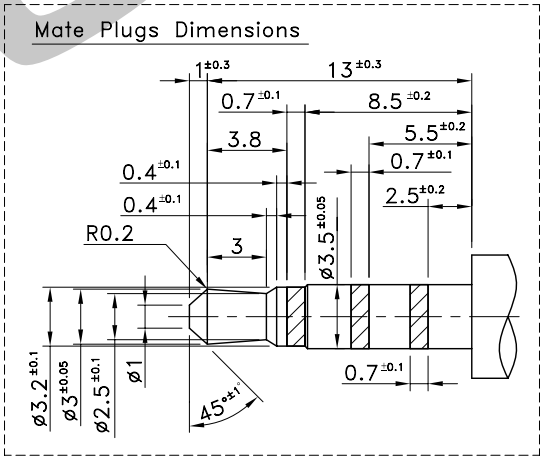
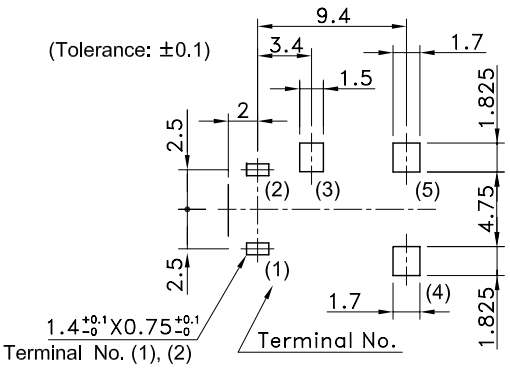
| No. | Parts | Material | Q'ty | Finish | Remarks |
|---|---|---|---|---|---|
| 6 | Break Terminal | t:0.25 Cu Alloy | 1 | Ep-Cu / Ni 1, Au0.1/ | |
| 5 | Chip Terminal | t:0.25 Cu Alloy | 1 | Ep-Cu / Ni 1, Au0.1/ | |
| 4 | Ring Terminal B | t:0.25 Cu Alloy | 1 | Ep-Cu / Ni 1, Au0.1/ | |
| 3 | Ring Terminal A | t:0.25 Cu Alloy | 1 | Ep-Cu / Ni 1, Au0.1/ | |
| 2 | Sleeve Terminal | t:0.25 Cu Alloy | 1 | Ep-Cu / Ni 1, Au0.1/ | |
| 1 | Body | PA | 1 | | Black |



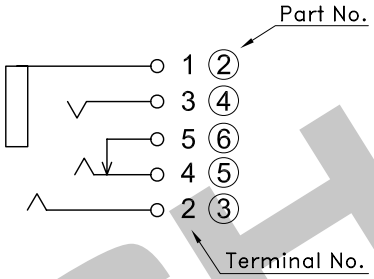



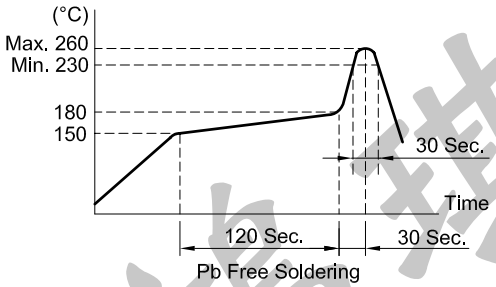

## P.C.B TERMINAL POSITION




## CIRCUIT ARRANGEMENT




## SOLDERING CONDITIONS




## SPECIFICATIONS

| | |
|---|---|
| 1. Rating | : DC 12V 1A |
| 2. Contact Resistance | : 30mΩ Max. |
| 3. Insulation Resistance | : 100MΩ Min. at DC 500V |
| 4. Dielectric Strength | : AC 500V for 1 Minute |
| 5. Insertion & Extraction Force | : 0.4~2.5kgf |
| 6. Life | : 5,000 Cycles |
| 7. Package | : 700 Pcs/Reel |
| 8. Operating Temperature Range | : -30~+80°C |
| 9. Storage Temperature Range | : -30~+80°C (Bulk)<br>: -20~+60°C (Taping) |
| 10. Reflow Soldering Profile | : According Reflow Profile<br>2 Times |
| 11. Manual soldering | : Tip Temperature 380±10°C<br>Soldering Time 3 +1 −0 Sec. |

| REVISION: | DATE: | REVISION: | DATE: |
|---|---|---|---|
| UNIT:mm | THIRD ANGLE PROJECTION METHOD | TOL. UNLESS OTHERWISE STATED:±0.3 | CODE NO.:HCH-1535-1 |

| ISSUED | CONFIRMED | | PART NO. |
|---|---|---|---|
| John | Elvis | HORNG CHIH<br>鴻琪股份有限公司 | PJK-646G |
| 2009.11.25 | 2009.11.25 | HCH® ISO9001 Certified ISO14001 Certified | |

鴻琪 HCH